
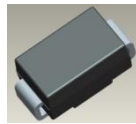


**Features**

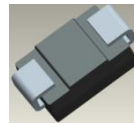
- Glass Passivated Die Construction
- Super-Fast Recovery Time for High Efficiency
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free "Green" Device (Note 3)**

**Mechanical Data**

- Case: SMA
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.064 grams (Approximate)



Top View



Bottom View

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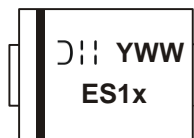
**Ordering Information** (Note 4)

| Part Number | Case | Packaging        |
|-------------|------|------------------|
| ES1x-13-F   | SMA  | 5000/Tape & Reel |

\* x = Device type, e.g. ES1A-13-F

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**



- ES1x = Product type marking code, ex. ES1A
- DII = Manufacturer's code marking
- YWW = Date code marking
- Y = Last digit of year (ex: 2 for 2002)
- WW = Week code (01 to 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

| Characteristic  | Symbol              | ES1A | ES1B | ES1C | ES1D | ES1G | Unit |   |
|---|---------------------|------|------|------|------|------|------|---|
| Peak Repetitive Reverse Voltage   | V <sub>RRM</sub>    |      |      |      |      |      |      |   |
| Working Peak Reverse Voltage  | V <sub>RWM</sub>    | 50   | 100  | 150  | 200  | 400  | V    |   |
| DC Blocking Voltage (Note 6)  | V <sub>R</sub>      |      |      |      |      |      |      |   |
| RMS Reverse Voltage   | V <sub>R(RMS)</sub> | 35   | 70   | 105  | 140  | 280  | V    |   |
| Average Rectified Output Current @ T <sub>T</sub> = +110°C  | I <sub>O</sub>      | 1.0  |      |      |      |      |      | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine-Wave Superimposed on Rated Load | I <sub>FSM</sub>    | 30   |      |      |      |      |      | A |

**Thermal Characteristics**

| Characteristic  | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Typical Thermal Resistance, Junction to Terminal (Note 5) | R <sub>θJT</sub>                  | 25          | °C/W |
| Operating and Storage Temperature Range                   | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C   |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   | Symbol             | ES1A         | ES1B | ES1C | ES1D | ES1G      | Unit |    |
|--|--------------------|--------------|------|------|------|-----------|------|----|
| Minimum Reverse Breakdown Voltage (Note 6)   I <sub>R</sub> = 5μA  | V <sub>(BR)R</sub> | 50           | 100  | 150  | 200  | 400       | V    |    |
| Maximum Forward Voltage Drop   I <sub>F</sub> = 0.6A<br>  I <sub>F</sub> = 1.0A                                  | V <sub>FM</sub>    | 0.90<br>0.92 |      |      |      | —<br>1.25 | V    |    |
| Peak Reverse Current at Rated DC Blocking Voltage (Note 6)   T <sub>A</sub> = +25°C<br>  T <sub>A</sub> = +125°C | I <sub>RM</sub>    | 5.0<br>200   |      |      |      |           |      | μA |
| Maximum Reverse Recovery Time (Note 7)   | t <sub>RR</sub>    | 25           |      |      |      |           |      | ns |
| Typical Total Capacitance (Note 8)   | C <sub>T</sub>     | 20           |      |      |      |           |      | pF |

- Notes:
5. Unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pad as heat sink.
  6. Short duration pulse test used to minimize self-heating effect.
  7. Measured with I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>RR</sub> = 0.25A. See figure 5.
  8. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

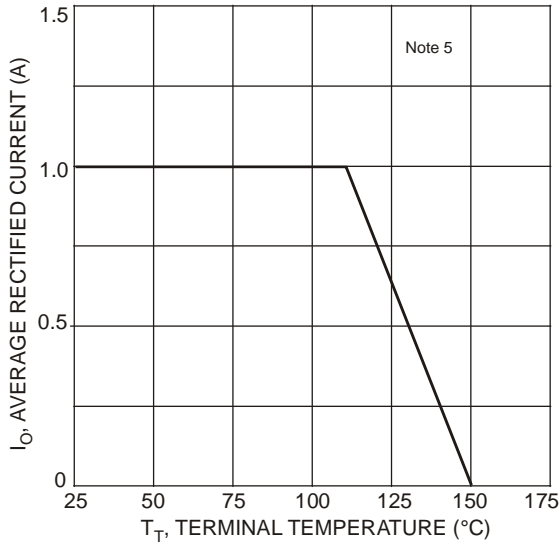


Fig. 1 Forward Current Derating Curve

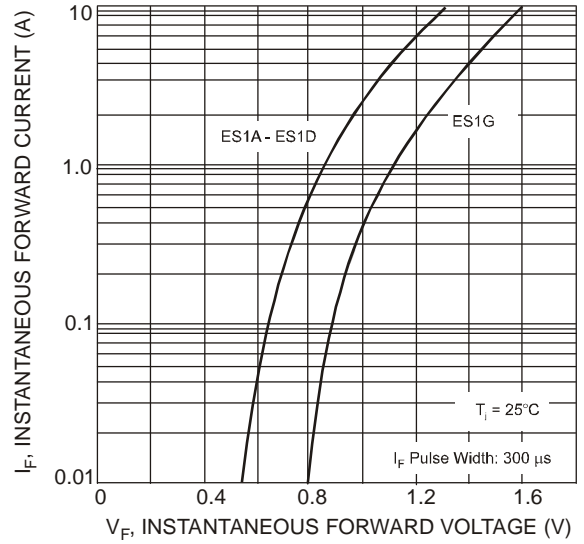


Fig. 2 Typical Forward Characteristics

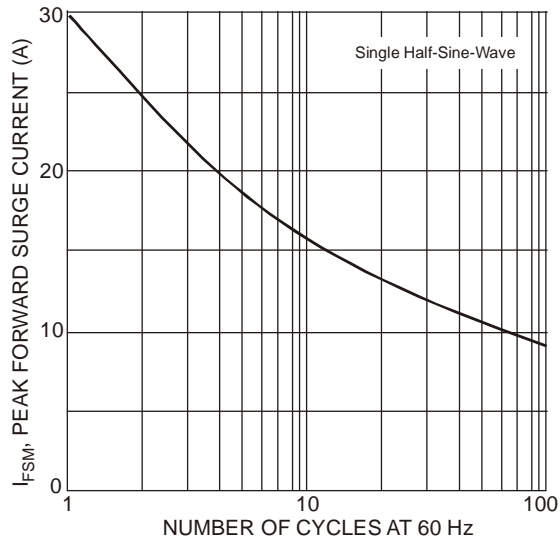


Fig. 3 Surge Current Derating Curve

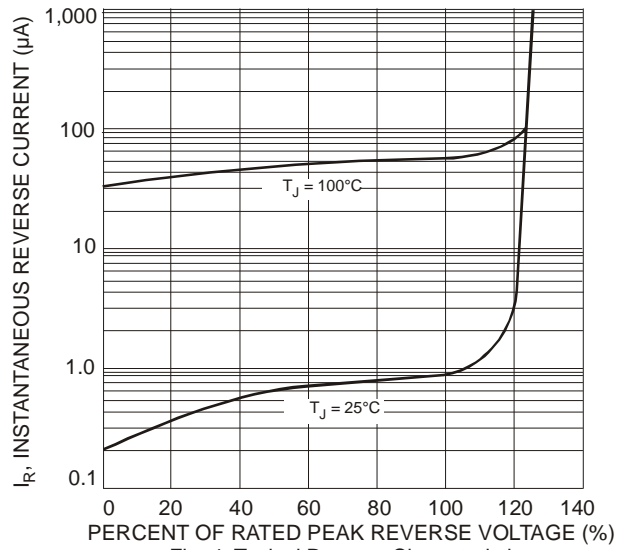
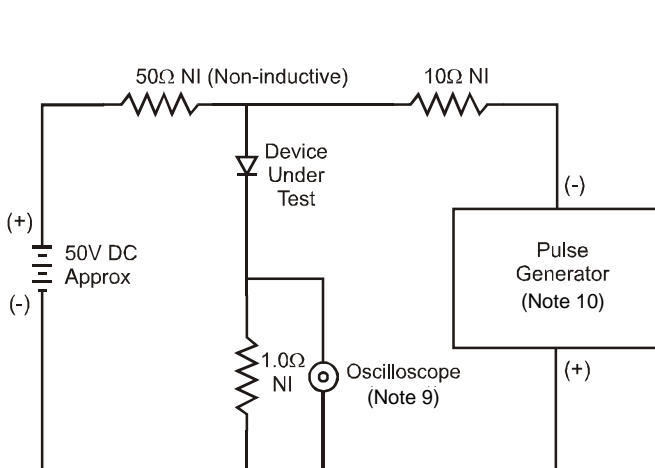


Fig. 4 Typical Reverse Characteristics



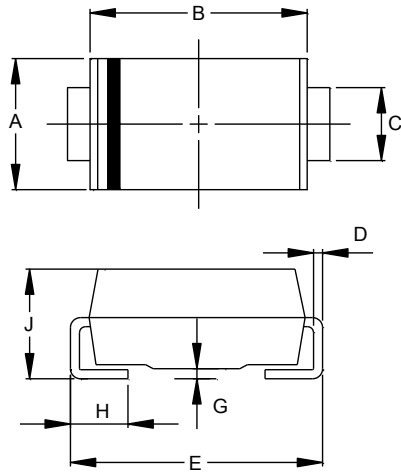
- Notes:  
 9. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.  
 10. Rise Time = 10ns max. Input Impedance = 50Ω.

Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

**Package Outline Dimensions**

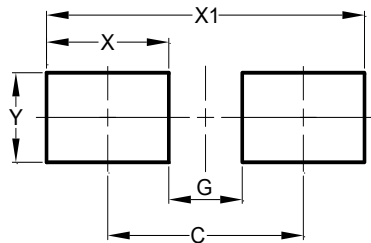
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| SMA                         |      |      |
|-----------------------------|------|------|
| Dim                         | Min  | Max  |
| A                           | 2.29 | 2.92 |
| B                           | 4.00 | 4.60 |
| C                           | 1.27 | 1.63 |
| D                           | 0.15 | 0.31 |
| E                           | 4.80 | 5.59 |
| G                           | 0.05 | 0.20 |
| H                           | 0.76 | 1.52 |
| J                           | 1.96 | 2.40 |
| <b>All Dimensions in mm</b> |      |      |

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 4.00          |
| G          | 1.50          |
| X          | 2.50          |
| X1         | 6.50          |
| Y          | 1.70          |

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